EOL of 25nm LPDDR4 6Gb-based (Z9AM) and 8Gb-based (Z91M) packages

PCN: 31913

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Type:	Die Shrink/Technology Transition, End of Life
Description:	Micron's 25nm LPDDR4 6Gb-based (Z9AM) and 8Gb-based (Z91M) packages are being replaced with 20nm process technology parts (Z0AM and Z01M) in line with Market requirements.
Reason:	Better Align With Industry Standard
Product Affected:	25nm LPDDR4 6Gb Z9AM 272b, 342b and 366b QDP packages will transition to 20nm LPDDR4 Z0AM packages 25nm LPDDR4 8Gb Z91M 272b QDP and 366b DDP & QDP packages will transition to 20nm LPDDR4 Z01M packages. *Note: The Z91M 272b DDP package will EOL and there will be no replacement part

Affected Micron Part Number	Recommended Replacement	Customer Part Number
Component		
MT53B256M64D2NH-062 WT:B		
MT53B256M64D2NK-062 WT:B	MT53B256M64D2NK-062 WT:C	
MT53B384M64D4NH-062 WT:A	MT53B384M64D4NH-062 WT:B	
MT53B384M64D4NK-062 WT:A	MT53B384M64D4NK-062 WT:B	
MT53B512M64D4NJ-062 WT:B	MT53B512M64D4NH-062 WT:C	
MT53B512M64D4NK-062 WT:B	MT53B512M64D4NK-062 WT:C	

*Materials that have been ordered are in **bold**.

Method of Identification:	Marketing Part Number
Micron Sites Affected:	All Sites
Qualification Plan:	20nm Z0AM and Z01M parts are currently in qualification process. Qualification data can be requested
Last Purchase Date*:	2016-11-02
Last Shipment Date:	2017-05-02

*Orders placed prior to the last purchase date are subject to current inventory levels, which may vary based on market conditions and customer demand. Early orders are encouraged.

NOTE: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change.

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